# Low Capacitance Surface Mount TVS for High-Speed Data Interfaces

The SRDA05–4 transient voltage suppressor is designed to protect equipment attached to high speed communication lines from ESD, EFT, and lightning.

#### Features:

- SO-8 Package
- Peak Power 500 Watts 8 x 20 μS
- ESD Rating:

IEC 61000-4-2 (ESD) 15 kV (air) 8 kV (contact)

IEC 61000-4-4 (EFT) 40 A (5/50 ns)

IEC 61000-4-5 (lightning) 23 (8/20 μs)

• UL Flammability Rating of 94V–0

# **Typical Applications:**

• High Speed Communication Line Protection

# **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Power Dissipation 8 x 20 μS @ T <sub>A</sub> = 25°C (Note 1)	$P_{pk}$	500	W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Lead Solder Temperature – Maximum 10 Seconds Duration	T <sub>L</sub>	260	°C

1. Non–repetitive current pulse 8 x 20  $\mu\text{S}$  exponential decay waveform

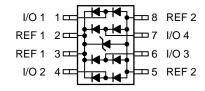


# ON Semiconductor®

http://onsemi.com

# SO-8 LOW CAPACITANCE VOLTAGE SUPPRESSOR 500 WATTS PEAK POWER 6 VOLTS

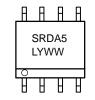
# PIN CONFIGURATION AND SCHEMATIC





SO-8 CASE 751 PLASTIC

# **MARKING DIAGRAM**



SRDA5= Device Code L = Location Code Y = Year

WW = Work Week

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
SRDA05-4R2	SO-8	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS**

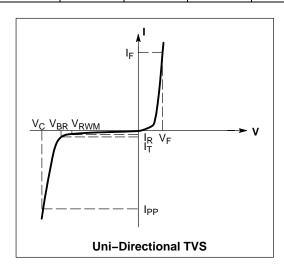
Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage @ I <sub>t</sub> = 1.0 mA	V <sub>BR</sub>	6.0	-	-	V
Reverse Leakage Current @ V <sub>RWN</sub> = 5.0 Volts	I <sub>R</sub>	N/A	-	10	μΑ
Maximum Clamping Voltage @ I <sub>PP</sub> = 1.0 A, 8 x 20 μS	V <sub>C</sub>	N/A	-	9.8	V
Maximum Clamping Voltage @ I <sub>PP</sub> = 10 A, 8 x 20 μS	V <sub>C</sub>	N/A	-	12	V
Between I/O Pins and Ground @ V <sub>R</sub> = 0 Volts, 1.0 MHz	Capacitance	-	10	15	pF
Between I/O Pins @ V <sub>R</sub> = 0 Volts, 1.0 MHz	Capacitance	-	5	8	pF

# **ELECTRICAL CHARACTERISTICS**

(T<sub>A</sub> = 25°C unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter		
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current		
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>		
$V_{RWM}$	Working Peak Reverse Voltage		
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>		
$V_{BR}$	Breakdown Voltage @ I <sub>T</sub>		
Ι <sub>Τ</sub>	Test Current		
$\Theta V_{BR}$	Maximum Temperature Coefficient of V <sub>BR</sub>		
lF	Forward Current		
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>		
Z <sub>ZT</sub>	Maximum Zener Impedance @ I <sub>ZT</sub>		
I <sub>ZK</sub>	Reverse Current		
Z <sub>ZK</sub>	Maximum Zener Impedance @ I <sub>ZK</sub>		



# **TYPICAL CHARACTERISTICS**

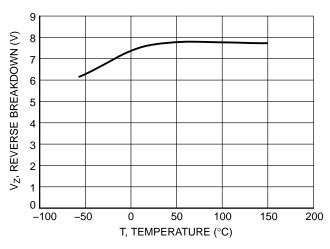


Figure 1. Reverse Breakdown versus Temperature

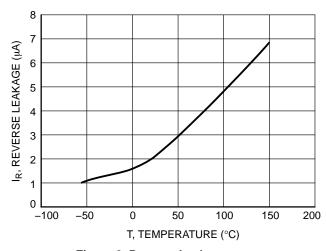


Figure 2. Reverse Leakage versus Temperature

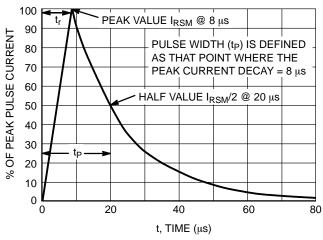


Figure 3.  $8 \times 20 \mu s$  Pulse Waveform

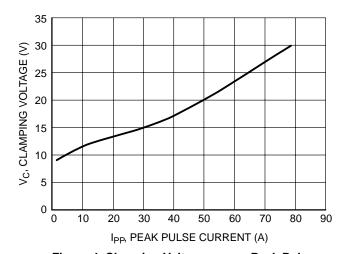
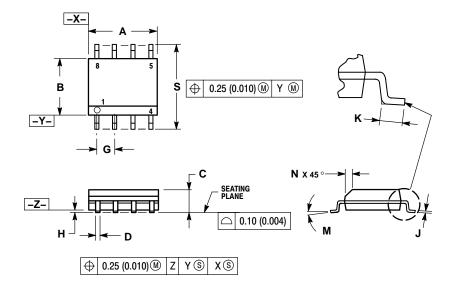


Figure 4. Clamping Voltage versus Peak Pulse Current

# **PACKAGE DIMENSIONS**

# SO-8 CASE 751-07 ISSUE AB

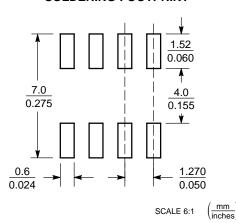


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
  Y14 5M 1982
- 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN
  EXCESS OF THE D DIMENSION AT MAXIMUM
  MATERIAL CONDITION
- MATERIAL CONDITION.
  6. 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDAARD IS 751–07

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
C	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27 BSC		0.050 BSC		
Н	0.10	0.25	0.004	0.010	
7	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
M	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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